

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6601xxxxPR-G

Typical Mass: 57 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.606	Silicon	10600	7440-21-3
		- Arsenic	<1	7440-38-2
Leadframe	20.083	Copper	352300	7440-50-8
		Tin	1100	7440-31-5
		Zinc	900	7440-66-6
		Chromium	1200	7440-47-3
		Silver	14100	7440-22-4
		Die attach	0.126	Silver
Epoxy	600	—		
Bonding wire	0.116	Gold	2000	7440-57-5
Resin	29.944	Silica	525300	60676-86-0
		Epoxy Resin	42900	—
		Phenol Resin	30900	—
		Metal Hydroxide	8400	—
Plating	0.430	Tin	7500	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."